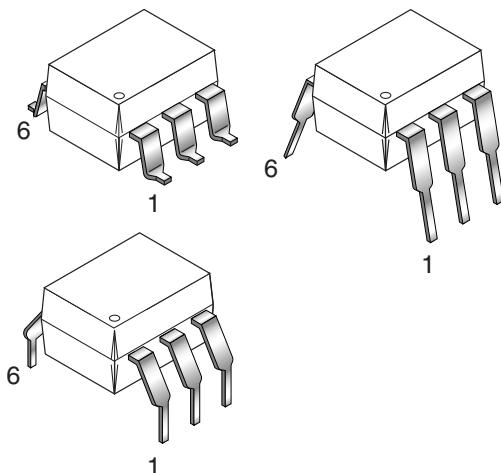


**H11L1M**

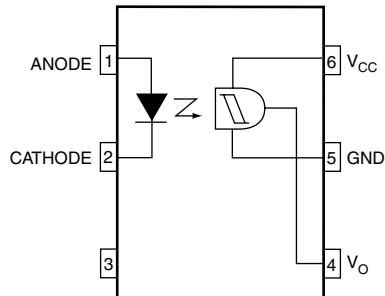
**H11L2M**

**H11L3M**

**PACKAGE**



**SCHEMATIC**



**DESCRIPTION**

The H11LXM series has a high speed integrated circuit detector optically coupled to a gallium-arsenide infrared emitting diode. The output incorporates a Schmitt trigger, which provides hysteresis for noise immunity and pulse shaping. The detector circuit is optimized for simplicity of operation and utilizes an open collector output for maximum application flexibility.

**FEATURES**

- High data rate, 1 MHz typical (NRZ)
- Free from latch up and oscillation throughout voltage and temperature ranges.
- Microprocessor compatible drive
- Logic compatible output sinks 16 mA at 0.4 V maximum
- Guaranteed on/off threshold hysteresis
- Wide supply voltage capability, compatible with all popular logic systems
- Underwriters Laboratory (UL) recognized—file #E90700, Volume 2
- VDE recognized – File#102497 – Add option V (e.g., H11LIVM)

**APPLICATIONS**

- Logic to logic isolator
- Programmable current level sensor
- Line receiver—eliminate noise and transient problems
- A.C. to TTL conversion—square wave shaping
- Digital programming of power supplies
- Interfaces computers with peripherals

**Truth Table**

Input	Output
H	L
L	H

**H11L1M**

**H11L2M**

**H11L3M**

**ABSOLUTE MAXIMUM RATINGS**

Parameters	Symbol	Device	Value	Units
<b>TOTAL DEVICE</b>				
Storage Temperature	$T_{STG}$	All	-55 to +150	°C
Operating Temperature	$T_{OPR}$	All	-40 to +85	°C
Lead Solder Temperature	$T_{SOL}$	All	260 for 10 sec	°C
Total Device Power Dissipation @ 25°C	$P_D$	All	250	mW
Derate Above 25°C			2.94	mW/°C
<b>EMITTER</b>				
Continuous Forward Current	$I_F$	All	60	mA
Reverse Voltage	$V_R$	All	6	V
Forward Current - Peak (1 µs pulse, 300 pps)	$I_F(pk)$	All	3.0	A
LED Power Dissipation 25°C Ambient	$P_D$	All	120	mW
Derate Linearly From 25°C			1.41	mW/°C
<b>DETECTOR</b>				
Detector Power Dissipation @ 25°C	$P_D$	All	150	mW
Derate Linearly from 25°C			2.0	mW/°C
$V_{45}$ Allowed Range	$V_O$	All	0 to 16	V
$V_{65}$ Allowed Range	$V_{CC}$	All	3 to 16	V
$I_O$ Output Current	$I_O$	All	50	mA

**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C Unless otherwise specified.)**

**INDIVIDUAL COMPONENT CHARACTERISTICS**

Parameters	Test Conditions	Symbol	Device	Min	Typ	Max	Units
<b>EMITTER</b>							
Input Forward Voltage	$I_F = 10 \text{ mA}$	$V_F$	All		1.2	1.5	V
	$I_F = 0.3 \text{ mA}$			0.75	1.0		
Reverse Current	$V_R = 3 \text{ V}$	$I_R$	All			10	µA
Capacitance	$V = 0, f = 1.0 \text{ MHz}$	$C_J$	All			100	pF
<b>DETECTOR</b>							
Operating Voltage Range		$V_{CC}$	All	3		15	V
Supply Current	$I_F = 0, V_{CC} = 5\text{V}$	$I_{CC(off)}$	All		1.6	5.0	mA
Output Current, High	$I_F = 0, V_{CC} = V_O = 15\text{V}$	$I_{OH}$	All			100	µA

**H11L1M**

**H11L2M**

**H11L3M**

**ISOLATION CHARACTERISTICS**

Parameters	Test Conditions	Symbol	Min	Typ	Max	Units
Input-Output Isolation Voltage	$t = 1 \text{ sec.}$	$V_{\text{ISO}}$	7500			$V_{\text{PEAK}}$
Isolation Capacitance	$V_{I-O} = 0V, f = 1 \text{ MHz}$	$C_{\text{ISO}}$		0.4	0.6	pF
Isolation Resistance	$V_{I-O} = \pm 500 \text{ VDC}$	$R_{\text{ISO}}$	$10^{11}$			$\Omega$

**TRANSFER CHARACTERISTICS**

DC Characteristics	Test Conditions	Symbol	Device	Min	Typ	Max	Units
Supply Current	$I_F = 10 \text{ mA}, V_{CC} = 5V$	$I_{CC(\text{on})}$	All		1.6	5.0	mA
Output Voltage, low	$R_L = 270\Omega, V_{CC} = 5V, I_F = I_{F(\text{on})} \text{ max.}$	$V_{OL}$	All		0.2	0.4	V
Turn-On Threshold Current	$R_L = 270\Omega, V_{CC} = 5V$	$I_{F(\text{on})}^*$	H11L1M			1.6	mA
			H11L2M			10.0	
			H11L3M			5.0	
Turn-Off Threshold Current	$R_L = 270\Omega, V_{CC} = 5V$	$I_{F(\text{off})}$	All	0.3	1.0		mA
Hysteresis Ratio	$R_L = 270\Omega, V_{CC} = 5V$	$I_{F(\text{off})}/I_{F(\text{on})}$	All	0.50	0.75	0.90	
AC Characteristics	Test Conditions	Symbol	Device	Min	Typ	Max	Units
SWITCHING SPEED							
Turn-On time	$R_L = 270\Omega, V_{CC} = 5V, I_F = I_{F(\text{on})}, T_A = 25^\circ\text{C}$	$t_{\text{on}}$	All			1.0	$\mu\text{s}$
						0.65	
						4	
Fall Time	$R_L = 270\Omega, V_{CC} = 5V, I_F = I_{F(\text{on})}, T_A = 25^\circ\text{C}$	$t_f$	All			0.1	$\mu\text{s}$
						.05	
						0.1	
Turn-Off Time	$R_L = 270\Omega, V_{CC} = 5V, I_F = I_{F(\text{on})}, T_A = 25^\circ\text{C}$	$t_{\text{off}}$	All			2.0	$\mu\text{s}$
						1.2	
						4	
Rise time	$R_L = 270\Omega, V_{CC} = 5V, I_F = I_{F(\text{on})}, T_A = 25^\circ\text{C}$	$t_r$	All			0.1	$\mu\text{s}$
						0.07	
						0.1	
Data Rate			All			1.0	MHz

**NOTE:**

\*Maximum  $I_{F(\text{on})}$  is the maximum current required to trigger the output. For example, a 1.6mA maximum trigger current would require the LED to be driven at a current greater than 1.6mA to guarantee the device will turn on. A 10% guard band is recommended to account for degradation of the LED over its lifetime. The maximum allowable LED drive current is 60mA.

**H11L1M**

**H11L2M**

**H11L3M**

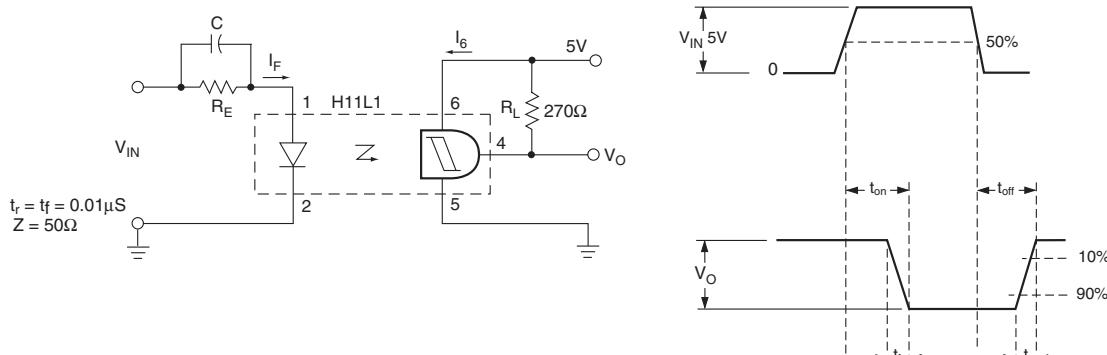


Figure 1. Switching Test Circuit and Waveforms

**TYPICAL PERFORMANCE CURVES**

Figure 2. Transfer Characteristics

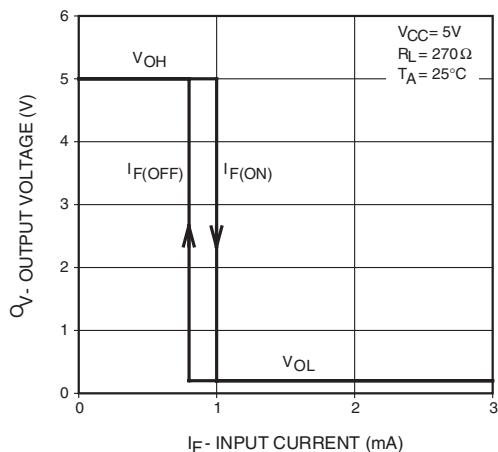


Figure 3. Threshold Current vs. Supply Voltage

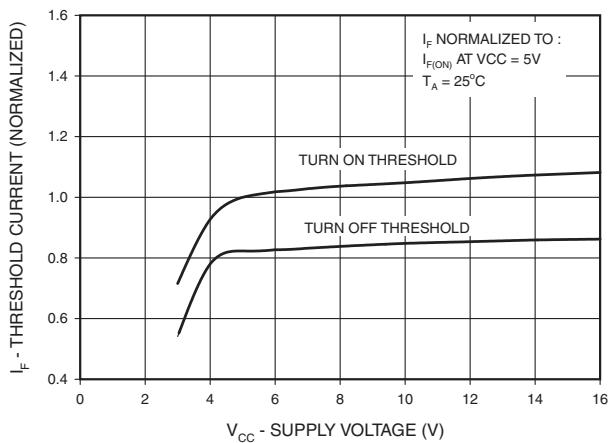


Figure 4. Threshold Current vs. Supply Temperature

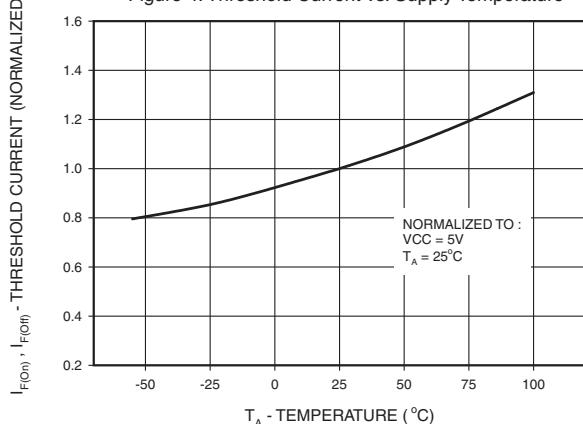
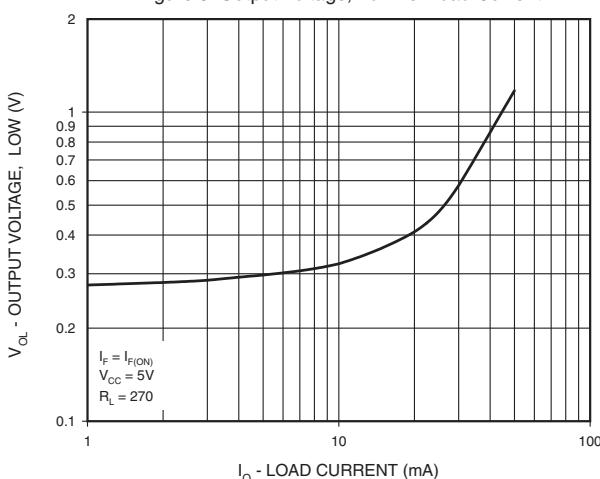


Figure 5. Output Voltage, Low vs. Load Current



**H11L1M**

**H11L2M**

**H11L3M**

**TYPICAL PERFORMANCE CURVES**

Figure 6. Supply Current vs. Supply Voltage

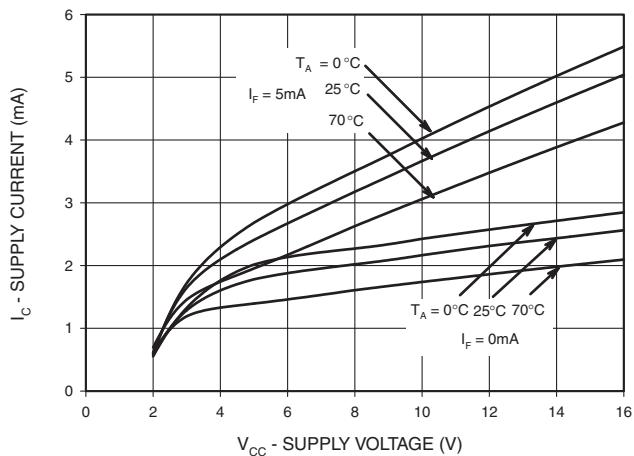
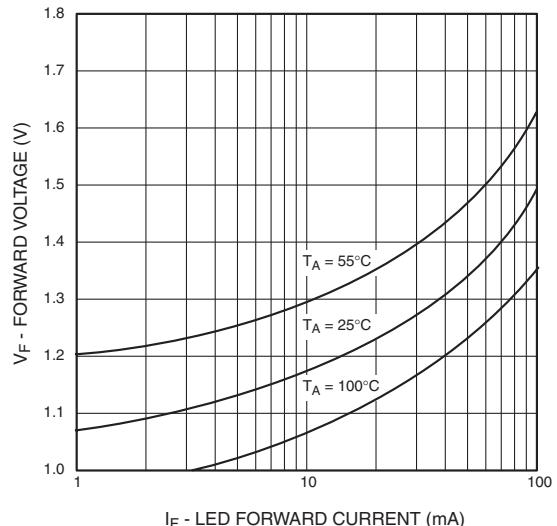


Figure 7. LED Forward Voltage vs. Forward Current

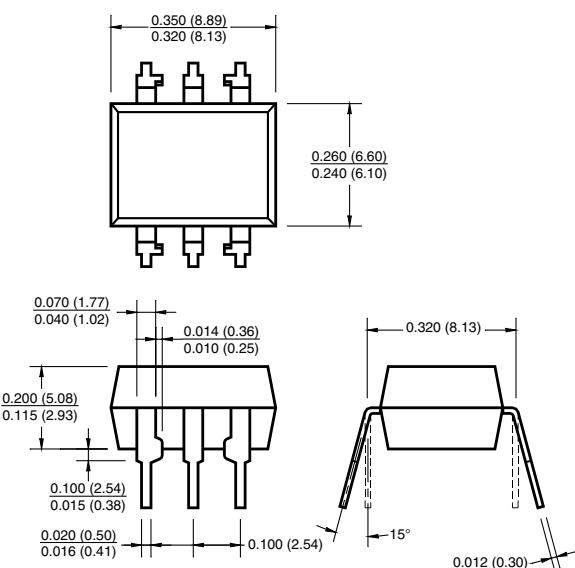


**H11L1M**

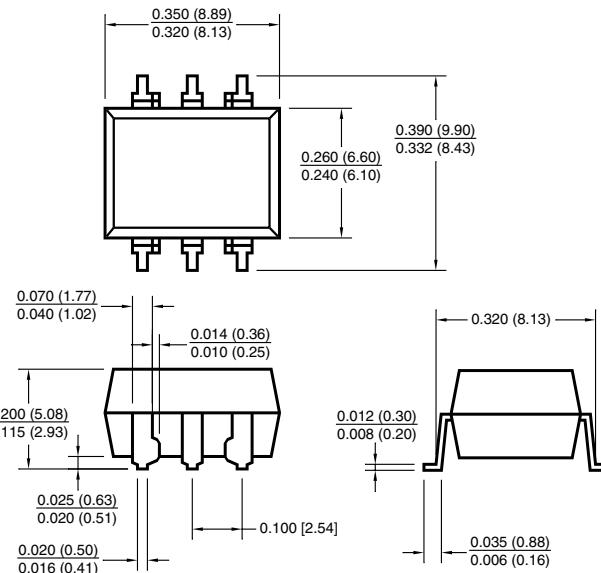
**H11L2M**

**H11L3M**

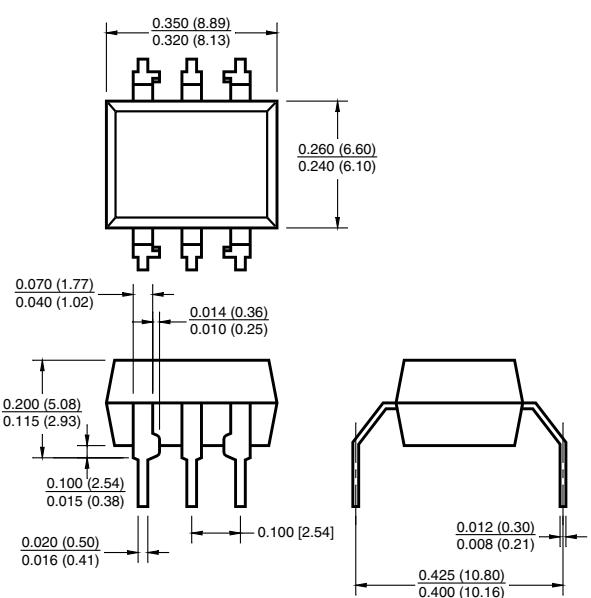
**Package Dimensions (Through Hole)**



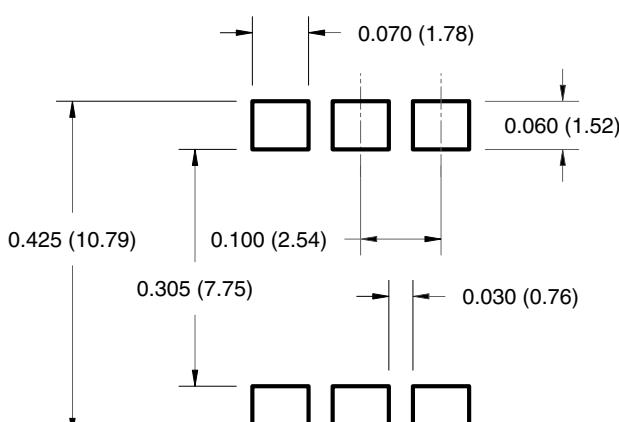
**Package Dimensions (Surface Mount)**



**Package Dimensions (0.4" Lead Spacing)**



**Recommended Pad Layout for Surface Mount Leadform**



**NOTE**

All dimensions are in inches (millimeters)

**H11L1M**

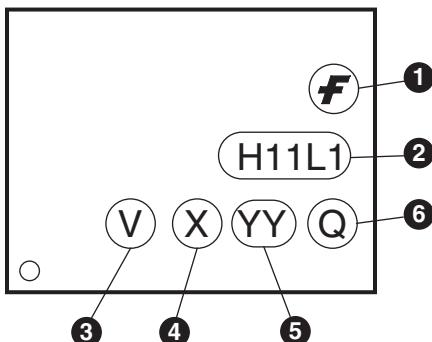
**H11L2M**

**H11L3M**

### ORDERING INFORMATION

Option/Order Entry Identifier	Description
S	Surface Mount Lead Bend
SR2	Surface Mount; Tape and reel
T	0.4" Lead Spacing
V	VDE 0884
TV	VDE 0884, 0.4" Lead Spacing
SV	VDE 0884, Surface Mount
SR2V	VDE 0884, Surface Mount, Tape & Reel

### MARKING INFORMATION



Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code, e.g., '3'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

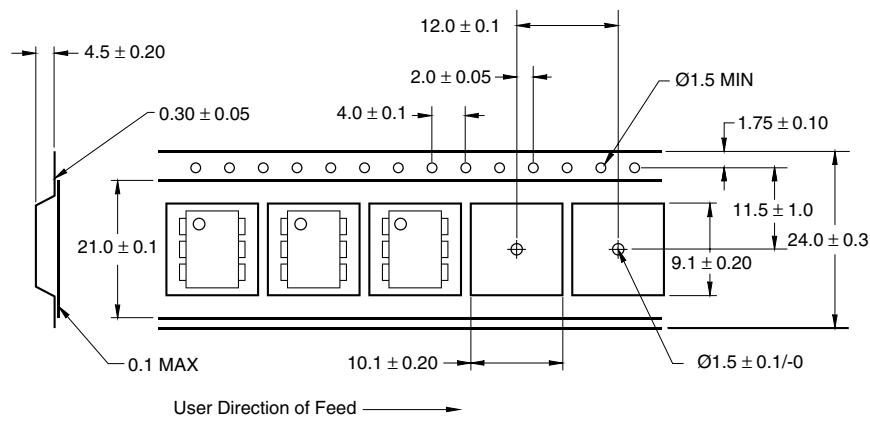
\*Note – 'V' option parts marked with date code '325' or earlier are marked in portrait format.

**H11L1M**

**H11L2M**

**H11L3M**

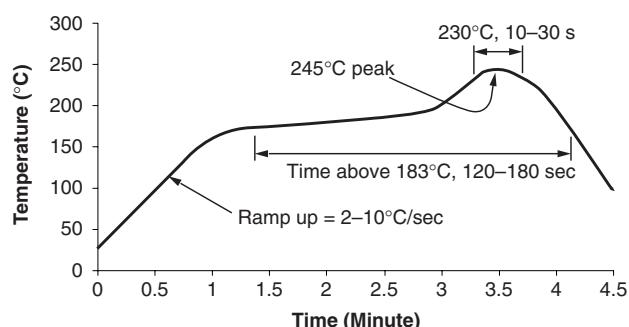
### Carrier Tape Specifications



### NOTE

All dimensions are in inches (millimeters)

### Reflow Profile



- Peak reflow temperature: 245°C (package surface temperature)
- Time of temperature higher than 183°C for 120–180 seconds
- One time soldering reflow is recommended



# 6-PIN DIP OPTOISOLATORS LOGIC OUTPUT

---

**H11L1M****H11L2M****H11L3M**

---

**DISCLAIMER**

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

**LIFE SUPPORT POLICY**

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ООО "ЛайфЭлектроникс"

"LifeElectronics" LLC

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибуторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибуторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помочь разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)  
Email: org@lifeelectronics.ru